

PRESS RELEASE

EuroCPS, a Horizon 2020 Project, Announces Next Round Of Support for Innovative Companies and their CPS projects

*The Innovative-company-support Project Started in February 2015.
15 EuroCPS Members from Nine Countries Are Now Supporting Nine Projects out of
the First Call. The Second Call for Industrial Projects Is Now open.*

GRENOBLE, France – Nov. 19, 2015 – [CEA-Leti](#), coordinator of the pan-European consortium EuroCPS, today announced that the 15 partners are continuing their support for SMEs, midcaps and large companies with the second open call for industrial projects, which is open from Oct. 28 to Dec. 2. Innovative cyber-physical system (CPS) projects can be submitted.

Innovative companies will have multiple support sources:

- Technical support from platform partner (indirect funding)
- Technical support from design center (indirect funding)
- Cascade funding support (direct funding)

EuroCPS project:

Funded by the European Commission, the three-year, €9.2 million project is designed to help innovators (SMEs, midcaps and large companies) overcome barriers they face when entering new markets by providing technical expertise, coaching and access to advanced industrial CPS platforms. It gets innovators up to speed on the innovation ecosystem of “smart” products by facilitating access to the latest technologies and their implementation. It also taps existing regional ecosystems in several countries to bring the full value chain – from hardware/software platforms to cyber-physical systems – to high value-added products and services.

Way of working and achievements:

EuroCPS partners were made aware of the innovative companies-support project via local network organizations, brokerage events, technical forums, exhibitions and the EuroCPS homepage (www.eurocps.org). More than 1,000 companies received notice of EuroCPS. Out of a high number of interested parties, 29 companies submitted industrial experiments during the first call. The proposals came out of seven countries, addressing hardware, software and Integration projects and utilized all platforms that are provided within EuroCPS:

- Avionics platform provided by Thales TRT
- iNEMO® platform provided by STMicroelectronics
- Integrated and open platform provided by AVL
- Power management and XMC platform provided by Infineon
- Quark platform provided by Intel
- Silicon processes and package technology platform provided by STMicroelectronics
- STM32F platform provided by STMicroelectronics

Two external and independent experts assessed the proposals, and based on their ranking, nine industrial experiments were selected for funding and have started projects.

The selected proposals show a huge variety of application areas, such as: low-power wireless connectivity, connected lighting, universal graphical data display, monitoring and optimization of different tasks in agri-food production, remote data tracking for vehicles by use of hardware in the loop systems, tracking of clinical test tubes, multi-core platform for avionic domain; human system interfaces and security control of cloud data.

In addition to the direct funding from the European Commission, the selected companies will get technical support from the platform partners and the following competence centers:

- CEA-Leti (France)
- Thales TRT (France)
- AVL LIST GmbH (Austria)
- Fraunhofer Institute for Integrated Systems and Device Technology (IISB) (Germany)
- The Digital Catapult (UK)
- Alma Mater Studiorum – University of Bologna (Italy)
- Lulea Tekniska Universitet (Sweden)
- Budapest University of Technology and Economics (Hungary)
- Finpower GmbH (Germany)

Second open call for industrial experiments:

After selection and start of the first CPS projects, EuroCPS will support a new set of innovative companies. Based on the feedback of several companies, Infineon and STMicroelectronics enlarged their platform to provide a broader portfolio for the second round. Proposals can be submitted from Oct. 28 to Dec. 2. The networking partners in EuroCPS are pleased to help the new entrant companies with registration, submitting proposals and finding the right platform and competence center. Selected projects will be notified the beginning of February 2016.

EuroCPS is part of the Smart Anything Everywhere Initiative under Horizon 2020 Leadership in Enabling Industrial Technologies, which aims to generating new and breakthrough technologies, boost competitiveness, create jobs and support growth by offering a Europe-wide network of design centers. A first group of four innovation actions included efforts under the combined 25M€ funding budget to support approximately 100 industrial experiments with the aim of involving more than 200 SMEs and midcaps in the field of cyber-physical systems (CPS), the Internet of Things (IoT) and smart systems integration (SSI).

More details on available competences, platforms and design centers are available at www.eurocps.org.

About CEA-Leti (France)

As one of three advanced-research institutes within the CEA Technological Research Division, CEA Tech-Leti serves as a bridge between basic research and production of micro- and nanotechnologies that improve the lives of people around the world. It is committed to creating innovation and transferring it to industry. Backed by its portfolio of 2,800 patents, Leti partners with large industrials, SMEs and startups to tailor advanced solutions that strengthen their competitive positions. It has launched 54 startups. Its 8,500m² of new-generation cleanroom space feature 200mm and 300mm wafer processing of micro and nano solutions for applications ranging from space to smart devices. With a staff of more than 1,800, Leti is based in Grenoble, France, and has offices in Silicon Valley, Calif., and Tokyo. Follow us at www.leti.fr and @CEA_Leti.

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